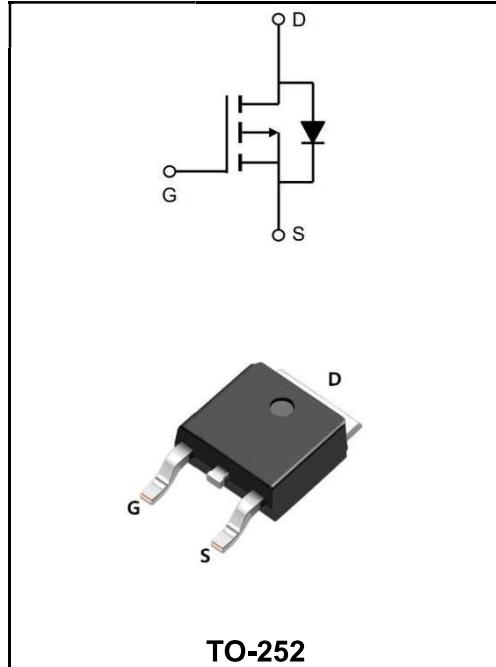


-200V P-CHANNEL ENHANCEMENT MODE MOSFET
MAIN CHARACTERISTICS

I_D	-4A
V_{DSS}	-200V
$R_{DS(on)-typ}(@V_{GS}=-10V)$	< 1.7Ω (Type: 1.4 Ω)


Application

- ◆ Power amplifier
- ◆ motor drive

Product Specification Classification

Part Number	Package	Marking	Pack
YFW4P20AD	TO-252	YFW 4P20AD XXXXX	2500PCS/Tape

Maximum Ratings at $T_c=25^\circ\text{C}$ unless otherwise specified

Characteristics	Symbols	Value	Units
Drain-Source Voltage	V_{DS}	-200	V
Gate - Source Voltage	V_{GS}	± 20	V
Continuous Drain Current $T_c=25^\circ\text{C}$	I_D	-4	A
Continuous Drain Current $T_c=100^\circ\text{C}$		-2.3	A
Pulsed Drain Current ^a	I_{DM}	-14	A
Single Pulse Avalanche Energy ^b	E_{AS}	310	mJ
Repetitive Avalanche Current ^a	I_{AR}	-3.6	A
Repetitive Avalanche Energy ^a	E_{AR}	4.2	mJ
Maximum Power Dissipation $T_c = 25^\circ\text{C}$	P_D	42	W
Maximum Power Dissipation (PCB Mount) ^e $T_A = 25^\circ\text{C}$		2.5	W
Peak Diode Recovery dV/dt ^c	dV/dt	-5.0	V/ns
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 to +150	°C
Maximum Junction-to-Ambient	$R_{\theta JA}$	110	°C/W
Maximum Junction-to-Ambient (PCB Mount) ^a	$R_{\theta JA}$	50	°C/W
Maximum Junction-to-Case (Drain)	$R_{\theta JC}$	3.0	°C/W

Maximum Ratings at T_c=25°C unless otherwise specified

Characteristics	Test Condition	Symbols	Min	Typ	Max	Units
Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =-250μA	V _{DS}	-200	-	-	V
V _{DS} Temperature Coefficient	Reference to 25°C , I _D =-1mA	ΔV _{DS/TJ}	-	-0.22	-	V/°C
Gate-Source Threshold Voltage	V _{DS} =V _{GS} , I _D =-250μA	V _{GS(th)}	-2.0	-3.5	-4.0	V
Drain-Source On-State Resistance	V _{GS} =-10V, I _D =-2 A ^b	R _{DS(ON)}	-	1.4	1.7	Ω
	V _{GS} =-5.5V, I _D =-1 A ^b		-	1.8	2.5	
Gate -Source Leakage	V _{GS} =±20V	I _{GSS}	-	-	±100	nA
Zero Gate Voltage Drain Current	V _{DS} =-200V , V _{GS} =0V	I _{DSS}	-	-	-100	μA
	V _{DS} =-160V , V _{GS} =0V , T _J =125°C		-	-	-500	
Forward Transconductance	V _{DS} =-50V , I _D =-2.2A	g _{fs}	1.1	-	-	S
Input Capacitance	V _{GS} =0V V _{DS} =-25V f=1MHz	C _{iss}	-	340	-	pF
Output Capacitance		C _{oss}	-	110	-	
Reverse Transfer Capacitance		C _{rss}	-	33	-	
Total Gate Charge	I _D =-3.9A V _{DS} =-160V V _{GS} =-10V	Q _g	-	-	20	nC
Gate-Source Charge		Q _{gs}	-	-	3.3	
Gate-Drain Charge		Q _{gd}	-	-	11	
Turn-on delay time	V _{DD} =-100V I _D =-3.9A R _G =18Ω R _D =24Ω see fig. 10 ^b	t _{d(on)}	-	8.8	-	ns
Rise Time		T _r	-	27	-	
Turn-Off Delay Time		t _{d(OFF)}	-	7.3	-	
Fall Time		t _f	-	19	-	
Continuous Source-Drain Diode Current	MOSFET symbol showing the integral reversep - n junction diode	I _s	-	-	-3.6	A
Pulsed Diode Forward Current ^a		I _{SM}	-	-	-14	A
Body Diode Voltage	T _J = 25 °C, I _s = - 3.6 A, V _{GS} = 0 V ^b	V _{SD}	-	-	-6.3	V
Body Diode Reverse Recovery Time	T _J = 25 °C, IF = - 3.9 A, dI/dt = 100 A/μs ^b	t _{rr}	-	150	300	ns
Body Diode Reverse Recovery Charge		Q _{rr}	-	0.97	2.0	μC
Forward Turn-On Time	Intrinsic turn-on time is negligible (turn-on is dominated by LS and LD)	t _{on}	-	-	-	-

Notes

1. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).

2. Pulse width ≤ 300 μs; duty cycle ≤ 2

Ratings and Characteristic Curves

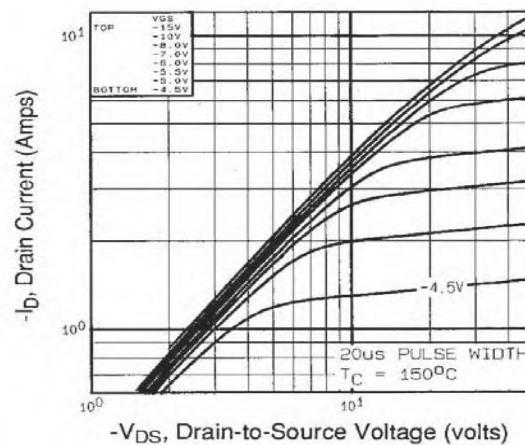
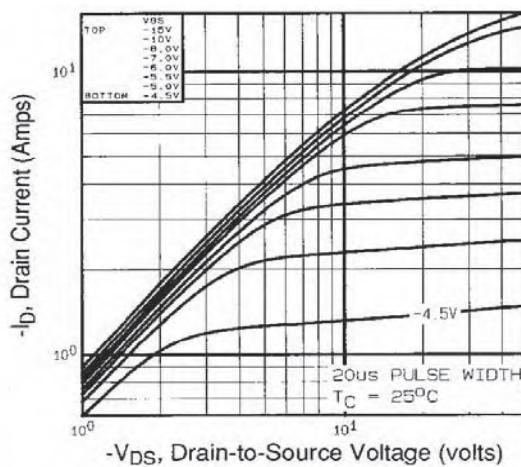
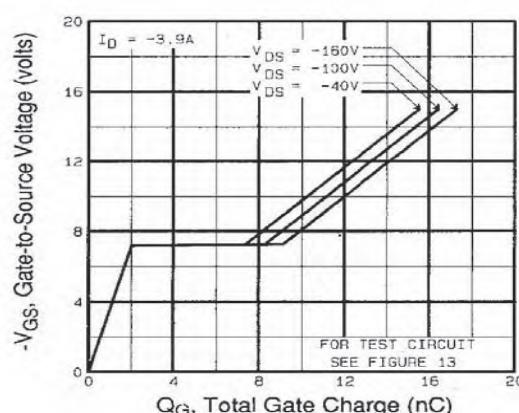
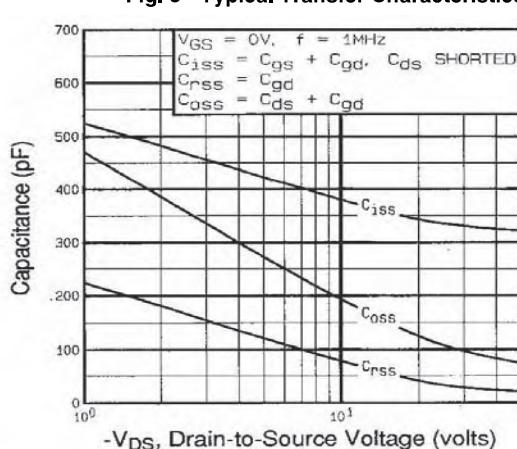
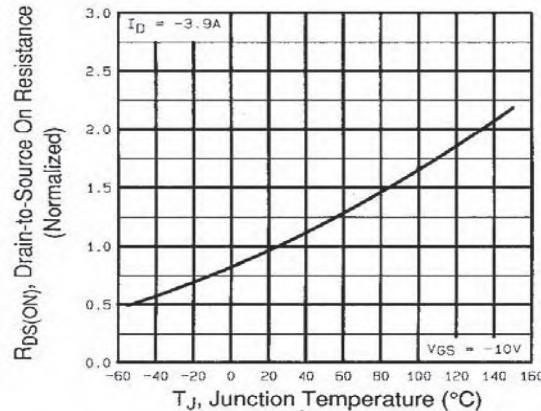
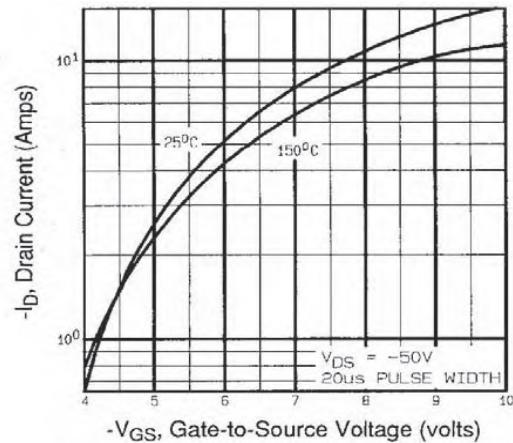
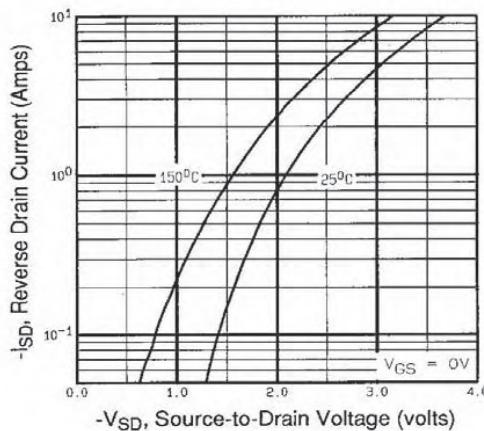
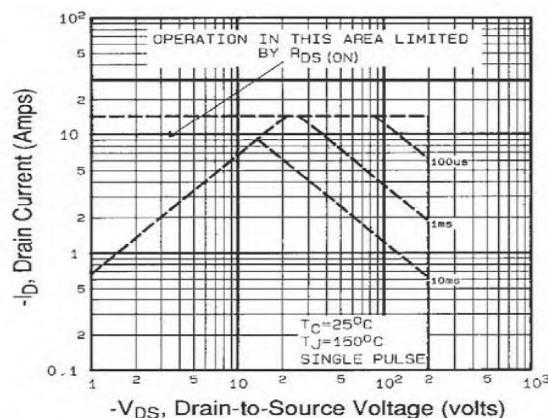
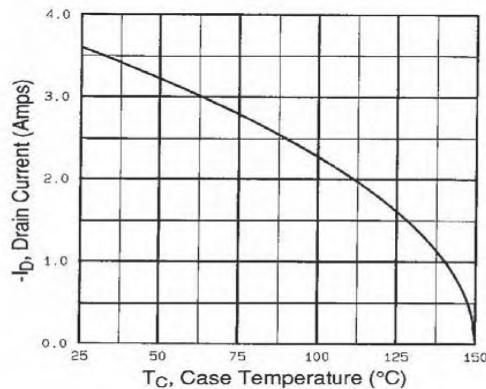
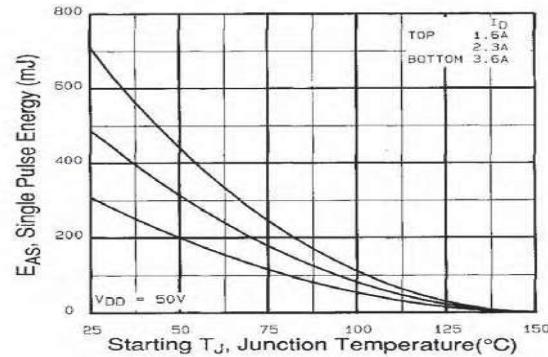
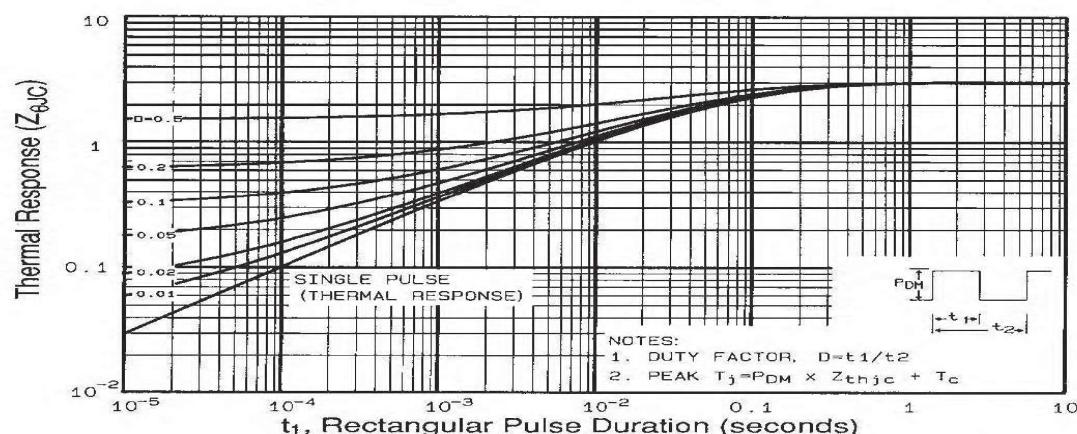


Fig. 1 - Typical Output Characteristics, $T_C = 25\text{ }^{\circ}\text{C}$



Ratings and Characteristic Curves

Fig. 7 - Typical Source-Drain Diode Forward Voltage

Fig. 8 - Maximum Safe Operating Area

Fig. 9. Maximum Drain Current Vs. Case Temperature

Fig. 10 - Maximum Avalanche Energy vs. Drain Current

Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

Package Outline Dimensions Millimeters

TO-252

The technical drawing illustrates the physical dimensions of a TO-252 package. Key dimensions include:
 - Top View: A (height), B (width), C (lead thickness), D (lead spread), E (lead spread), F (lead spread), G (lead spread), H (height), B2 (lead spread), and D1 (lead spread).
 - Side View: A2 (lead spread), C2 (lead thickness), D (lead spread), E1 (lead spread), and L (lead spread).
 - Detail A: Shows lead thickness C2 and lead spread V1.
 - Detail A2: Shows lead spread L2.

Dim.	Min.	Typ.	Max.
A	2.10	-	2.50
A2	0	-	0.10
B	0.66	-	0.86
B2	5.18	-	5.48
C	0.40	-	0.60
C2	0.44	-	0.58
D	5.90	-	6.30
D1	5.30REF		
E	6.40	-	6.80
E1	4.63	-	-
G	4.47	-	4.67
H	9.50	-	10.70
L	1.09	-	1.21
L2	1.35	-	1.65
V1	-	7°	-
V2	0°	-	6°

All Dimensions in millimeter